

Title (en)

PRESSURE SUPPORT FOR AN ELECTRONIC CIRCUIT

Title (de)

DRUCKUNTERSTÜTZUNG FÜR EINE ELEKTRONISCHE SCHALTUNG

Title (fr)

SUPPORT DE PRESSION POUR CIRCUIT ÉLECTRONIQUE

Publication

EP 2415076 A2 20120208 (DE)

Application

EP 10713602 A 20100330

Priority

- EP 2010054147 W 20100330
- DE 102009015757 A 20090401

Abstract (en)

[origin: WO2010112478A2] The invention relates to a circuit design comprising an electrical circuit, which comprises at least one electronic component attached to a substrate and a flat conductor track for electrically contacting the component, wherein on the electrical circuit an elastic element is provided and furthermore a device for applying a force to the elastic element is present so that the elastic element is pressed onto the electrical circuit. The crack formation in a solder under the component is thereby prevented.

IPC 8 full level

H01L 23/48 (2006.01)

CPC (source: EP KR US)

H01L 23/32 (2013.01 - KR); **H01L 23/36** (2013.01 - KR); **H01L 23/48** (2013.01 - KR); **H01L 24/24** (2013.01 - EP US); **H01L 24/25** (2013.01 - EP US); **H01L 24/72** (2013.01 - EP US); **H01L 24/82** (2013.01 - EP US); **H01L 25/072** (2013.01 - EP US); **H01L 24/29** (2013.01 - EP US); **H01L 2224/24011** (2013.01 - EP US); **H01L 2224/2402** (2013.01 - EP US); **H01L 2224/24051** (2013.01 - EP US); **H01L 2224/24225** (2013.01 - EP US); **H01L 2224/24226** (2013.01 - EP US); **H01L 2224/291** (2013.01 - EP US); **H01L 2224/29191** (2013.01 - EP US); **H01L 2224/32225** (2013.01 - EP US); **H01L 2224/45147** (2013.01 - US); **H01L 2224/73267** (2013.01 - EP US); **H01L 2224/82039** (2013.01 - EP US); **H01L 2924/00011** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/0102** (2013.01 - EP US); **H01L 2924/01023** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/01074** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/13055** (2013.01 - EP US); **H01L 2924/15787** (2013.01 - EP US)

Citation (search report)

See references of WO 2010112478A2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)

WO 2010112478 A2 20101007; **WO 2010112478 A3 20110811**; CN 102365734 A 20120229; CN 102365734 B 20150819; DE 102009015757 A1 20101014; EP 2415076 A2 20120208; JP 2012523109 A 20120927; KR 20120002982 A 20120109; RU 2011144091 A 20130510; US 2012075826 A1 20120329

DOCDB simple family (application)

EP 2010054147 W 20100330; CN 201080015502 A 20100330; DE 102009015757 A 20090401; EP 10713602 A 20100330; JP 2012502627 A 20100330; KR 20117022978 A 20100330; RU 2011144091 A 20100330; US 201013262582 A 20100330